

REMARKS

Claims 12-37, 51-82 and 84-86 are pending in the above-identified application.

Claims 12-37, 51-57, 62-66, 68-82, and 84-86 were allowed. Claims 58-61 and 67 were rejected. With this Amendment, claims 58-60 and 67 were cancelled and claim 61 was amended. Accordingly, claims 12-37, 51-57, 61-66, 68-82 and 84-86 are at issue in the above-identified application.

35 U.S.C. § 103 Obviousness Rejection of Claims

Claims 58-61 were rejected under 35 U.S.C. § 103(a) as being unpatentable over *Yahiro et al.* (U.S. Patent No. 6,204,509) in view of *Mitome et al.* (U.S. Patent No. 5,695,897). Claim 67 was rejected under 35 U.S.C. § 103(a) as being unpatentable over *Yahiro et al.* in view of *Mitome et al.* further in view of *Saitoh et al.* (U.S. Patent No. 5,319,444). Applicants respectfully traverse these rejections.

Amended claim 61 recites a method of making a mask, which mask has a plurality of pattern formation regions in which mask circuit patterns are formed, and a supporting region in which any mask circuit pattern is not formed, said supporting region being provided for holding said plurality of pattern formation regions while separating said plurality of pattern formation regions from each other, wherein said supporting region has first alignment marks used at the time of exposure of said mask for forming said mask circuit patterns thereon, second alignment marks used at the time of exposure of a substrate to be exposed for forming circuit patterns thereon, said method comprising the step of forming all of said first alignment marks and said second alignment marks on said mask at one time, wherein said first alignment marks and said second alignment marks are formed on a mask board by selectively removing said mask board *to form holes or grooves in said mask board and burying said holes or grooves with a metal whose atoms have atomic weights heavier than those of atoms*

of said mask board. None of the above cited references, either alone or in combination, teach or suggest a mask board to form holes or grooves in said mask board and burying said holes or grooves with a metal whose atoms have atomic weights heavier than those of atoms of said mask board. Claims 58-60 and claim 67 have been cancelled. Applicants respectfully traverse these rejections. Withdrawal of these rejections are respectfully requested.

In view of the foregoing, Applicants submit that the application is in condition for allowance. Notice to that effect is requested.

Respectfully submitted,

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